

SPECIFICATION

Revised A : 4/Apr./'07 ER Revised B: 07/Mar./'08 KY Revised C : 9/Jun./'08 KY

1. PART NUMBER

Part Number	Packaging	Quantity
MM8130-2600B	Bulk Package	
MM8130-2600RA2	178 mm dia. reel	2000 pcs/reel
MM8130-2600RB8	330 mm dia. reel	8000 pcs/reel

2. MECHANICAL

C> B>

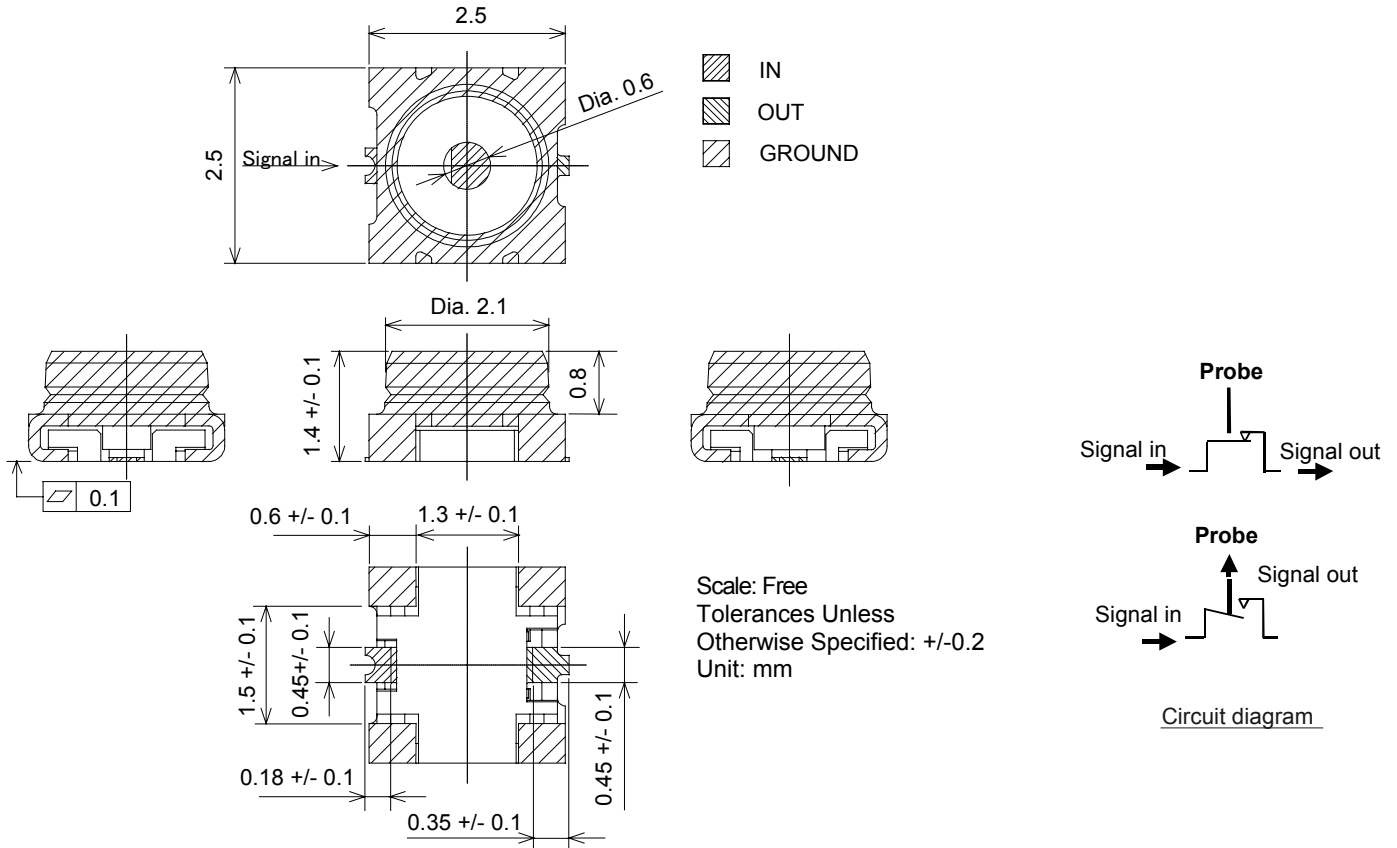
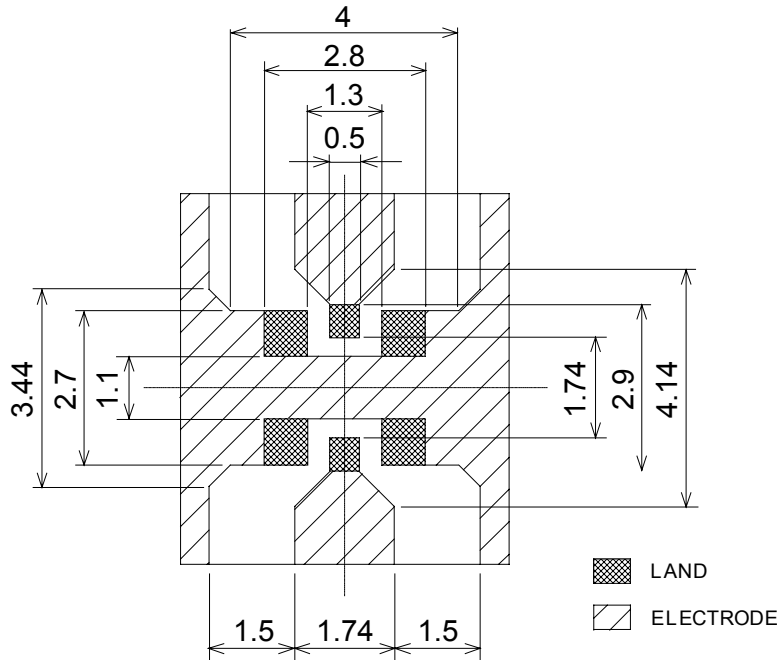


FIGURE1.Construction

3. RATING :

Item	Specification
Voltage Rating	250V r.m.s. maximum
Nominal Frequency Range	DC to 6GHz
Nominal Impedance	50Ω
Temperature Rating	-40°C to +85°C
Insulation Resistance	500 MΩ minimum
Withstanding Voltage	AC 300V±20V
B> Initial Contact Resistance (without conductor resistance)	Center contact 70.0mΩmax.
Voltage Standing Wave Ratio (V.S.W.R.)	Meet the requirements of following spec. 1.2 max. (DC to 3GHz) 1.3 max. (3GHz to 6GHz)
Insertion Loss	0.1dBmax. (DC~3GHz) 0.2dBmax.(3GHz ~6GHz)
Isolation	20dBmin.(DC~3GHz) 15dBmin.(3GHz ~6GHz)
Durability	100 cycles

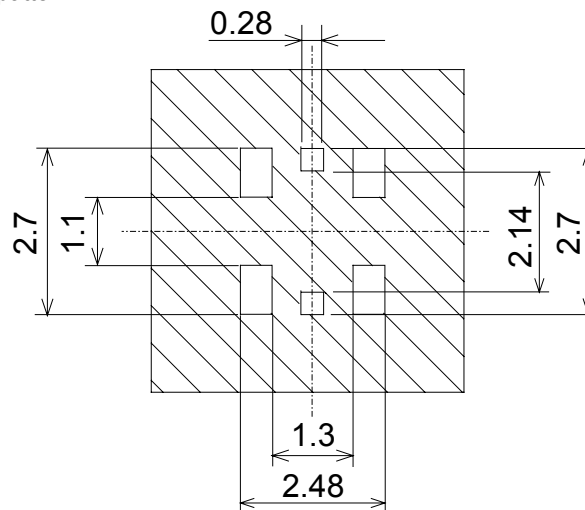
4. STANDARD PATTERN DIMENSION



(Note) ·I/O pattern should be designed to be the impedance match 50 ohm.
 ·The material of PCB is the epoxy resin of glass fabric base. ($\epsilon_r=4.8$). Thickness is 1.0mm.
 ·The solder resist should be printed except for the land pattern on the PCB
 FIGURE2. Standard pattern dimensions

5. STANDARD STENCIL MASK PATTERN

The standard stencil mask pattern is as FIGURE 3. (Thickness is 0.12mm)
 There is the possibility to have the contact failure by solder shifting into contact point, if the excess solder is used by non standard stencil mask pattern



Unit: mm

The standard solder cream metal stencil mask drawing (Thickness : 0.12mm)
 Note) There is the possibility to have the contact failure by solder shifting into contact point, if the excess solder is used by non standard stencil mask pattern.

FIGURE3. Standard stencil mask pattern